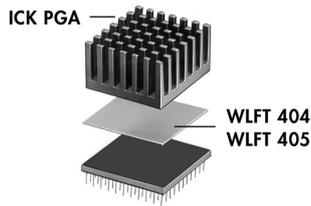


Data sheet Product ICK PGA 21 x 21



Heatsinks and active heatsinks for processors>Heatsinks for PGA
53,3 x 53,3 x 16,5 mm, for IC design PGA and others

Features

way of fixation:	<ul style="list-style-type: none"> • therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	53.34 mm
height:	16.51 mm
plate thickness:	5 mm
length:	53.34 mm
thermal resistance:	7 - 1.9 K/W
dissipation loss:	8.6 W
surface:	black anodised

Technical Drawing

